



## IC Knowledge – 2008 IC Cost Model Supported Packages List

March 21, 2008 the following processes are included in the 2008 IC Cost Model.

The prefix for each package type is p for plastic, c for ceramic and fc for flip chip.

1. Bumped die
2. Bumped die with coating
3. cBGA
4. cLGA
5. cPGA
6. DIP
7. fcBGA
8. fcLGA
9. fcPGA
10. LQFP
11. MLF/MLP
12. MQFP
13. pBGA
14. pPGA
15. PLCC
16. SOIC
17. SOJ
18. TQFP
19. TSOP